OptoTech

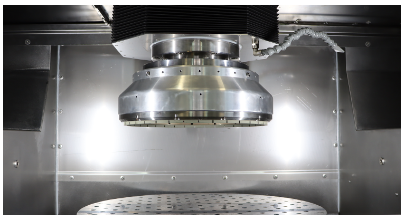
SMP 801 CNC

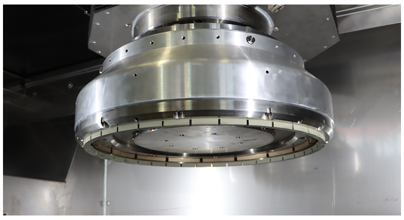
Pre-, Fine and Optional Finest Grinding of Plano Surfaces

CNC-controlled plano grinding machine SMP 801 CNC with KombiTool Technology for cut to polish quality and optional second tool spindle for finest processing (3C–Technology).

Technical Data

	SMP 801 CNC
Working Range Diameter	0 mm - 800 mm
Clamping Technology	Vacuum Table or Magnetic Table
Tool Spindles	Speed: 0 - 2850 rpm; Interface: Flange
Workpiece Spindle	Speed: 0 - 250 rpm; Interface: Flange
Vacuum	-0.6 bar
Air Pressure Requirement	6 bar
Power Requirement (others on request)	37 kW
Dimensions	Width: 2600 mm, Height: 2850 mm, Depth: 2800 mm
Weight (approx.)	8000 kg





Highlights

- Two step processing in one work cycle with the KombiTool / KombiTool+ [link] (combined rough and fine grinding tool)
- Optional third processing step using diamond pellet tool or diamond foil tool (3C-Technology, requires second Z-Axis)
- Precise plano surfacing to polishable quality due to optimised grinding parameters with multi-cut technology, adjusted speed and feed rates for all spindles
- New drive concepts with highly dynamic digital drives for all axes
- Microsoft Windows operating system with OptoTech user interface, graphically controlled, ensuring shorter set-up times
- Design according to current EMV- and CE-requirements

System Advantages

- High precision surface generation
- Optimized machining parameters for cut-to-polish grinding
- 3C-Technology Option for even better surface qualities and up to 30-50% shorter polishing cycle times

Options

- 2nd Tool Spindle with integrated 2nd Z-Axis for 3C Technology (TwinCut-Version)
- Vacuum Table, Magnetic Table, Combined Vacuum and Magnetic Table
- OptoTech KombiTool and Plano Finest Grinding Tool
- Hydro Expansion Clamping Technology for standard plano tools